



High-Performance Interconnect Solutions for EV Charging & EVSE Infrastructure Applications

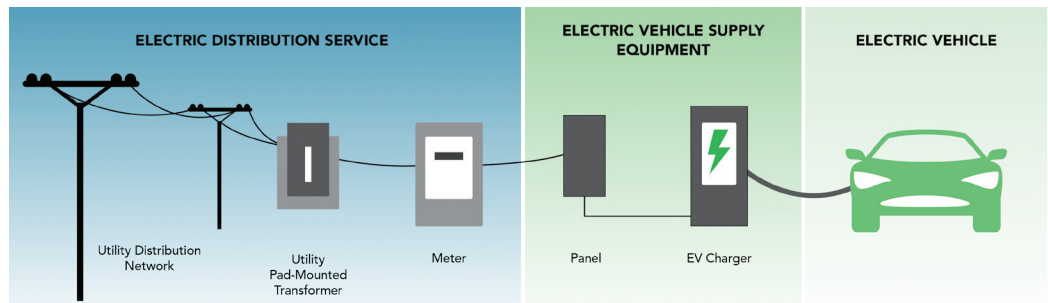
The demand for increased charging power continues to grow as more electric vehicles hit the roadways. Reliable and accessible charging infrastructure is needed to support long-range mileage with fast and efficient, on-demand charging solutions.

Samtec offers rugged and high-power solutions for reliable connectivity to support power conversion, thermal management, and the current or future needs of the electric vehicle.



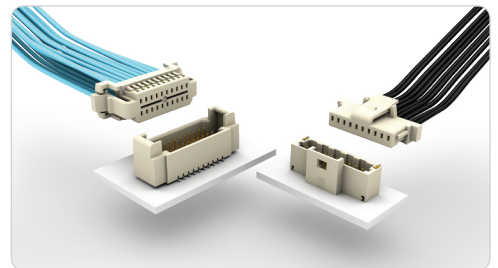
Applications Include:

- On-board Chargers
- Electric Vehicle Service Equipment (EVSE)
- AC Level 1 & 2 Charging
- DC Fast Charging
- V2G Smart Energy Management Solutions



On-board chargers convert AC to DC power for electric vehicles, but they also ensure a safe and efficient charge. By monitoring charging conditions and type, the onboard charger provides flexibility while ensuring reliable functionality.

Micro Mate™ 1.00 mm pitch discrete wire systems are just one example of Samtec's high-performance interconnect solutions that provide reliable connection with design flexibility to assist with power management inside a vehicle. *(Continued on Next Page)*



Samtec is IATF 16949, ISO 14001 and ISO 9001 certified, and is fully integrated with in-house tooling, plating, and automated manufacturing capabilities that provide for advanced development, low-cost, quick turn, and high-volume production. In addition, Samtec is compliant with International Traffic and Arms Regulations (ITAR) and with EU WEEE and RoHS directives.

SAMTEC HIGH-PERFORMANCE INTERCONNECTS

Samtec offers a wide variety of interconnect solutions to support charging infrastructure-related needs, including:

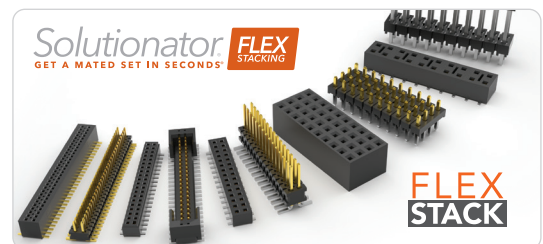
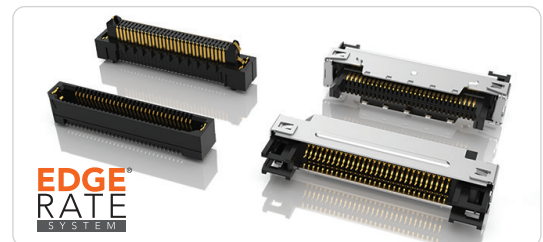
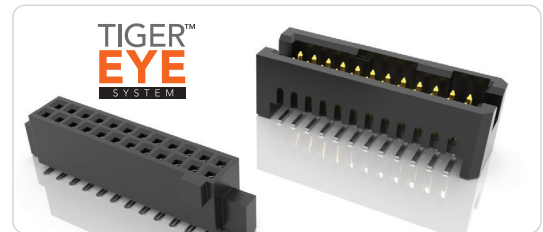
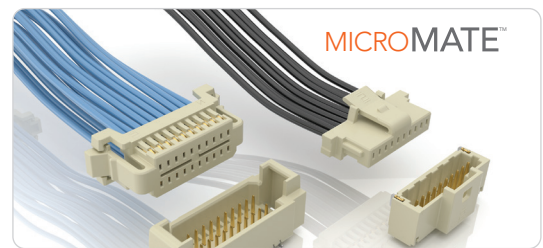
Micro Mate™ 1.00 mm Pitch Discrete Wire Systems support cable-to-board, cable-to-cable, and panel-to-board applications. A crimp-style dual leaf contact system provides reliable connection, and a rugged positive latching option offers increased retention.

Tiger Eye™ Rugged Systems are available in three pitches (0.80 mm, 1.27 mm & 2.00 mm), these micro rugged interconnects feature Samtec's Tiger Eye contact system for high reliability and high cycle applications. The multi-finger, BeCu contacts provide redundant points of contact, along with the best combination of mechanical and electrical properties.

mPOWER® 2.00 mm Pitch Micro Power System with 18 Amp power blade interconnects for board-to-board, cable-to-board and cable-to-cable applications. Other high-power connectors and rugged connectors up to 60 A, are available in small form factors and elevated designs with power blades or individually shrouded power pins.

High-Speed Board-to-Board Systems include mezzanine designs with integral ground planes, high-density arrays, backplane interconnects, rugged signal integrity optimized Edge Rate® systems, and high-speed performance to 56 Gbps NRZ/112 Gbps PAM4. Products are available in a variety of pitches, stack heights, and configurations for maximum routing, grounding, and design flexibility.

Flexible Stacking Systems: Samtec has more ways to connect two or more boards than any other interconnect provider. The variety and design flexibility of our standard pitch (2.54, 2.00, 1.27 mm), two-piece board-to-board interconnects is unmatched. The **Flex Stacking Solutionator®** identifies, in under one minute, the mating connector sets that meet your design requirements.



Further Reading, Downloads & Resources:



samtec.com/automotive



samtec.com/quality



**EV Charging
eBrochure**



**Automotive
Solutions Catalog**